

IN THE SPECIFICATION

Please amend the specification as follows (Clean copies appear below; a marked-up version showing the amendments is attached as an Appendix hereto):

Clean copy of the first full paragraph of page 1, lines 3 to 10:

BACKGROUND OF THE INVENTION

1. Field of the Invention

B¹ This invention relates to a ceramic heater used for drying in a semiconductor industry, and more particularly to a ceramic heater facilitating temperature control, which is thin and light, and a method of producing the same as well as an electrically conductive paste used for the formation of a heating element of the heater.

Clean copy of the second full paragraph of page 1, lines 11 to 19:

2. Discussion of Background Information

B Typical semiconductor products are manufactured by applying an etching resist onto a silicon wafer and then etching. In this case, a photosensitive resin is applied onto the surface of the silicon wafer and is dried after the application. The resin coated silicon wafer is generally placed on a heater in order to dry the coating.

Clean copy of the paragraph bridging pages 2 and 3, i.e., page 2, line 23 to page 3, line

9:

SUMMARY OF THE INVENTION

The present invention relates to a ceramic material having an excellent heat conductivity. In particular, a nitride ceramic or carbide ceramic is used as a substrate for a heater instead of a metal such as aluminum or the like. It was discovered that such a ceramic substrate does not cause warping or strain even when the substrate is made thin. The ceramic substrate can rapidly and easily conduct temperature and is excellent in controlling the temperature by changing voltage or current applied to the heating body.

Clean copy of the sixth full paragraph of page 7, lines 18 to 20:

BRIEF DESCRIPTION OF THE DRAWINGS

B4 Fig. 1 is a plan view of a ceramic heater according to the present invention;

Clean copy of the third full paragraph of page 8, lines 8 to 16:

DETAILED DESCRIPTION OF THE PRESENT INVENTION

B5 The ceramic heater according to the present invention is a heater comprising a ceramic substrate made of an insulative nitride ceramic or carbide ceramic and a heating body formed on one surface of the ceramic substrate by printing and the other surface thereof being used as a heating face for heating a semiconductor product such as silicon wafer or the like placed thereon.
